

ABSTRACT OF THE DISCLOSURE

A tape carrier package has a chip, a tape carrier and sealing material. The chip has an active surface on which a plurality of bump electrodes are centrally arranged in two rows. The tape carrier has a device hole smaller than the chip, and has a plurality
5 of leads each of which is divided into inner lead and outer lead. The inner leads are routed inward the center of the device hole and connected to the bump electrodes, respectively. The sealing material encapsulates the active surface of the chip and the inner leads, with the outer leads being exposed.